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CME
region of the one side, the wiring pattern formed over the penetrating holes, a part of the adhesive material formed on internal wall surfaces forming the penetrating holes so as not to stop up the penetrating holes.

C3
55. (Amended) A substrate having penetrating holes formed therein, the substrate having a wiring pattern directly formed over a particular region including the penetrating holes on one side thereof, the substrate having protrusions formed in the internal wall surfaces of the penetrating holes by the material constituting the substrate.

C4
58. (Amended) The substrate as defined in claim 53, wherein the wiring pattern includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.

59. (Amended) The substrate as defined in claim 55, wherein the wiring pattern includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.

66. (Amended) A method of manufacturing a substrate comprising:

C5
providing a substrate with an adhesive material provided on one surface thereof;

carrying out punching from the side of the substrate on which the adhesive material is provided and in the direction of the opposite side thereof to form penetrating holes and to draw a part of the adhesive material into the penetrating holes; and

adhering a wiring pattern over a particular region on the one surface including the penetrating holes on the substrate through the adhesive material.

67. (Amended) A method of manufacturing a substrate comprising providing a substrate of a material of a higher elasticity than external electrodes, having penetrating holes in which the internal wall surfaces have protrusions, and having a wiring pattern directly formed over a region including the penetrating holes.